RESEARCH

Study the Efect of Silicon Nanofuid on the Heat Transfer Enhancement of Triangular‑Shaped Open Microchannel Heat Sinks

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Received: 21 May 2023 / Accepted: 3 September 2023 / Published online: 19 September 2023 © The Author(s), under exclusive licence to Springer Nature B.V. 2023

Abstract

Comparative investigations were carried out for open and closed microchannel heat sinks for water and SiO2/water nanofuid, varying the Reynolds number from 200 to 800 and modifying the fn height from 0.5 mm to 2.0 mm. As part of its microchannel heat sink performance analysis, the study looked at several variables, including the Nusselt number, pressure drop, and cross-sectional fluid flow pattern and evaluated the optimum fin height. Nano SiO₂/water coolant enhances the Nusselt no. indicated that MCHS with 1.5 mm fn height has the most signifcant heat transfer value of 53.02. In contrast, MCHS with a 2.0 mm fin height has 38.68 using water as coolant. Water and nano SiO₂/water coolants had a maximum pressure drop of 187.90 and 286.96 Pa at 2.0 mm in height. The MCHS with 1.0 mm fn height has the maximum TPF of 2.17 and 1.75 for nano Sio₂/water and water as a coolant, respectively. TPF was increased by 24.19% and 46.24%, respectively, compared to water as a coolant and a closed microchannel heat sink in the triangular-shaped open MCHS with SiO₂/water nanofluid and 1.0 mm of fn height.

Keywords Sustainable energy · Renewable practices · Reliable energy · Clean energy · Energy efficiency

Nomenclature

- ρ Density (kg/m³)
- u, v Velocity component (m/s)
- k Thermal conductivity (W/m^oC)
- *Dh* Hydraulic diameter (m)
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- T Temperature ($^{\circ}C$)
- t Time (s)
- A Area (m^2)
- C_p Specific heat (kJ/kg K)
h Heat transfer coefficien
- h Heat transfer coefficient $(W/m^2 K)$
- P Pressure (Pa)
- q Heat flux (W/m^2)
- R_e Reynolds number
- $N_{\rm u}$ Nusselt number

1 Introduction

Over the past few decades, integrated circuit capabilities have improved so that billions of circuits may be manufactured on a single tiny chip. However, a more efective cooling system is required to keep the chip functioning since the heat fux is much greater. The microchannel heat sink (MCHS) heat transfer rate is higher than conventional heat exchangers, making the system more compact and less cumbersome. These benefts have led to the widespread use of MCHS in various industrial sectors. Traditional electronic devices often use fns and air as coolants for their microchips and microtubes. The quantity of heat produced by modern technology has increased over the years, but the poor thermal conductivity of air has made it harder for heat to dissipate. Therefore, liquid cooling is more efficient than air cooling in enhancing the thermal performance factor [[1](#page-14-0)]. Geometrical elements such as the microchannel pattern, the number of inlets and outlets, the cross-section shape, nanofluids, and phase change materials influence the efficiency of the cooling process.

Tuckerman and Pease [[2](#page-14-1)] initially used the term "microchannel cooling system" in 1981. Microchannel cooling is a passive way to eliminate heat from electronic devices that don't take up as much space as other methods. An MCHS with a uniform geometrical layout is often used to efficiently remove heat from electronic components. As the capacity and use of microelectronic equipment have dramatically expanded, more heat is generated inside these devices. Smooth MCHS simply isn't going to make it when dealing with such a high-temperature spike. Because of this, smooth MCHS needs enhancements to its thermal performance factor (TPF). Adding additional surfaces or cavities to the smooth channel may increase the TPF of the MCHS. TPF parameters such as Nusselt number and pressure drop will be compared between the modifed and smooth channels. Several scientists are working toward increasing the heat dissipation rate with minimum pres-sure loss [[3–](#page-14-2)[6](#page-14-3)]. In the research, two significant strategies for heat transfer via single-phase coolant have mainly been used by adjusting channel design, which allows high heat disposal and increases coolant properties to transport more heat, such as dielectric, nanofuid, and refrigerant. Coolants, including oil, nanofuid, water, refrigerant, etc., have all been investigated. Although water is the most common coolant, nanofuids have recently gained popularity due to their ability to transport heat efficiently [[7](#page-14-4)]. Nanofluids are flled with nanoparticles, which are small enough to pass through most materials. But nanofuid has several restrictions, such as sedimentation, higher pressure loss, and pipe wall abrasion from particle suspensions [[8,](#page-14-5) [9](#page-14-6)]. Much work is being put in to address these concerns and ensure the safe usage of nanofuid in MCHS. Considerable expansion potential remains in this industry, especially for the coolant with outstanding heat transfer capacity, which is constantly preferred.

According to the research of Sui et al. [[10](#page-14-7)], wavy rectangular microchannels have better thermal performance than straight baseline microchannels. The MCHS with rectangular, trapezoidal, and triangular cross sections were studied statistically by Wang et al. [[11](#page-14-8)]. They found that trapezoidal microchannels had the highest thermal resistance, followed by triangular microchannels, out of the three possible MCHS geometries (rhombus, circular, and hexagonal). Hexagonal shapes, as shown by Alfaryjat et al. [[12\]](#page-14-9), are optimal for heat transfer. The most signifcant friction factor and heat resistance values were found in the rhombus cross-section. Deng et al. [[13\]](#page-15-0) investigated the properties of a copper microchannel with a form. Compared to traditional MCHS with a rectangular cross-section, the study indicated that the Nusselt number increased by 39% and heat resistance decreased by 22%. Other forms, such as those with cavities [[14,](#page-15-1) [15\]](#page-15-2), ribs [[16](#page-15-3), [17](#page-15-4)], and segmented fns [\[18](#page-15-5), [19](#page-15-6)], have also been discussed in the literature. A microchannel's surface roughness and shape afect heat transmission and fluid flow $[20, 21]$ $[20, 21]$ $[20, 21]$ $[20, 21]$. Research has shown that surface roughness increases the pressure drop but has less efect on heat transmission.

Converging microchannels with very hydrophobic walls were studied by Ermagan and Rafee [[22](#page-15-9)]. They noted that the highly hydrophobic walls enhanced TPF for pumping power. Pin fns with a staggered confguration in an MCHS were studied by Yang et al. [[23\]](#page-15-10) in five distinct shapes such as hexagon, square, pentagon, triangle, and circle. They conducted both numerical and experimental experiments with water and discovered that triangular pin fins had the most blocking efects, whereas circular pin fns had the least. The fn's hexagonal cross-section provides the best heat conduction. Studies on oblique or segmented layouts of the fns demonstrate that additional fow paths improve fuid mixing, distort the thermal barrier layer, and redevelop it, leading to a higher heat transfer rate [[24](#page-15-11)]. Sajedi et al. [[25\]](#page-15-12) conducted a numerical investigation of microchannels with both circular splitter plates. To minimize pressure, drop over the heat sink; splitter plates help drop the flow separation. Chein and Huang [[26\]](#page-15-13) studied electronic components' functional behavior and reported that nanofuids have a more signifcant cooling impact.

The effects of Al2O3/water and SiO2/water nanofluids on TPF in a square cross-section cupric conduit were experimentally studied by Nassan et al. [[27](#page-15-14)] under constant heat fux conditions. SiO2/water nanofuid was given a higher TPF than Al2O3/water nanofluid. The turbulent flow condition of Al2O3, TiO2, and SiO2 nanofuids at diferent ratios was studied by Rostamani et al. [\[28\]](#page-15-15) in a 2D conduit. The particle ratio in volume was discovered to infuence the TPF in nanofuids. Convective heat transfer through a circular tube with laminar fow and a constant wall temperature boundary condition was experimentally explored by Heris et al. [[29](#page-15-16)]. The results showed that the heat transfer coefficient of SiO2 and Al2O3 nanofluids increases with both increasing the nanoparticle concentration and the Peclet number. Heris et al. [[30](#page-15-17)] investigated the effects of SiO2, TiO2, and Al2O3 nanofuids in turbine oil on heat transmission using a circular tube. The performance index for every nanofuid under investigation was determined to be greater than one. They concluded that the nanofuid-based coolants were the most efective at transmitting heat. Pin fns and surface roughness were assessed for their respective importance by Sadaghiani and Kosar [[31\]](#page-15-18). The heat transfer coefficient surrounding a fin in an MCHS was expected to be maximal near the wake's trailing edge downstream of the pin fn, which was confrmed by Wang et al. [\[32\]](#page-15-19). As the fn height varied, he discovered a heat sink confgured openly with a fin height of 75% to 80% was more efficient at transferring heat than a heat sink confgured closed. The author has outlined the advantages of an open MCHS [\[33](#page-15-20)].

Similarly, Yin et al. [\[34](#page-15-21)] reported that flow boiling instabilities might be significantly suppressed in the hollow microchannel, in addition to heat transmission improvements. In addition, Kadam et al. [\[35\]](#page-15-22) demonstrated the advantages of an open MCHS over a closed MCHS. In addition, a summary of research done on the MCHS is provided in Table [1](#page-3-0).

A signifcant research gap exists regarding exploring optimal fn height in MCHS, with limited studies conducted in this area. Additionally, there is a notable scarcity of research comparing the performance of open and closed MCHS configurations. In Open MCHS, the fin height is lower than the channel height allowing the fuid to flow between the fin top surface and the MCHS cover. As the fn height varies, the open space available above the fn height varies and vice versa. In Closed MCHS, the fn height equals the MCHS channel height, resulting in a fn top surface touching the MCHS cover. There has been little known work on fn design compared with open and closed MCHS.

Consequently, the proposed study aims to identify the heat transfer potential and overall performance of an open and closed MCHS consisting of a triangular fn. A comparative fnding is performed by varying the open MCHS fn height from 0.5 mm, 1.0 mm, and 1.5 mm and the closed MCHS fn height of 2.0 mm. In addition, the optimal value of fn height that provides superior heat transfer and fuid fow characteristics has been determined by a thorough comparison of various heat sinks. An extensive comparative investigation is conducted by interchanging the fuid between water and nano SiO2/water as the fuid and varying the laminar fow Re from 200 to 800. Several factors, including fuid fow pattern, Nusselt number, and pressure drop, are considered while assessing the MCHS's performance. For this reason, the index for performance assessment criteria is developed and evaluated across all forms at diferent Reynolds numbers, such as the thermal performance factor.

2 Geometric Confguration

Figure [1](#page-4-0) depicts the schematic representation of an MCHS. The reduced fne height demonstrates the open MCHS appearance that has formed in proportion to the channel height. The upper surface of the fin is thus separated from the heat sink surface by fuid. It's common knowledge that the shorter the fn, the more space below it, and likewise, in the other direction. The arrangement's coolant flows via the channel and the empty area. With this setup, the fns are submerged completely in the coolant, which frequently transfers heat to the fns' outer surface. Its circulation is distinct from that in a closed microchannel, which confnes fuid to those specifc routes. In this investigation, we use computational methods to examine the heat sinks' three-dimensional shape. As shown in Fig. [1,](#page-4-0) the physical dimensions of the computing domain are 27 mm in length, 10 mm in width, and 3 mm in height. The structure comprises a group of triangular pin fns of varied heights. The layout of the fns consists of four rows of 12 individual fns. Hence, there are 48 identical fns spaced out 1 mm from one another in a rectangular formation. As was previously indicated, the ideal confguration for the microchannel heat sink was discovered by varying the pin fn height. Almost every conceivable MCHS cross-section is considered, and the flow patterns on each cross-section and their impact on pressure drop and heat transfer at diferent Reynolds numbers are investigated.

3 Numerical Simulation

3.1 Governing Equations

The pressure loss and heat transfer in 3D geometry were simulated using ANSYS 2022 R1. The momentum equations regarding velocity and pressure have been solved using the SIMPLE Method Equation. To streamline our simulation models, we make a few assumptions. There was a laminar and incompressible steady-state flow condition, the influence of viscosity on heat dissipation and gravity was disregarded, and natural convection and radiation heat transfer were also disregarded. The governing equations are as follows, based on the assumptions above:

The energy equation for the liquid [[31](#page-15-18)]

$$
\rho_f C_{p_f} \frac{\partial T}{\partial t} + \rho_f C_{p_f} \left(\overrightarrow{U} \cdot \nabla T \right) = k_f \nabla^2 T \tag{1}
$$

The energy equation for the solid [\[31\]](#page-15-18)

$$
\rho_s C_{p_s} \frac{\partial T}{\partial t} = k_s \nabla^2 T \tag{2}
$$

Mass conservation equation [\[31\]](#page-15-18)

$$
\rho \nabla \bullet (\overrightarrow{U}) = 0 \tag{3}
$$

Momentum equation [[31\]](#page-15-18)

1 3**Table 1** A summary of diferent MCHS

 (c)

Fig. 1 Schematic representation of MCHS (**a**) Top view (**b**) Side view (**c**) Isometric view

$$
\rho_f \frac{\partial \vec{U}}{\partial t} + \rho_f \left(\vec{U} \cdot \nabla \right) \vec{U} = -\nabla p + \mu \nabla^2 \vec{U}
$$
\n(4)

4 Boundary Conditions

The heat sink material was considered copper, while the coolant was a water and nanofluid SiO2/water mixture of 0.15% of volume fraction. Table [2](#page-5-0) depicts the material properties. The combined heat transfer solution is then employed to address the issue. The following are some of the steady-state assumptions made throughout this study: The fluid is incompressible and follows a Newtonian distribution; the flow is laminar and steady; and the adiabatic conditions and nonslip properties of the MCHS walls are preserved.

A SIMPLE method equation is incorporated into the simulation. For more precise simulation results, a secondorder upwind method and set the convergence criterion to 10^{-6} . Figure [2](#page-5-1) depicts the applied boundary condition in the domain of the numerical setup. All heat sinks and exterior walls are assumed adiabatic, and uniform heat fux was provided to their bottom surfaces. The no-slip boundary

 $\vec{U} = -\nabla p + \mu \nabla^2 \vec{U}$ (4) condition on the inside walls was considered, and the outlet boundary condition was adjusted to the atmospheric pressure outlet. The inlet velocity varies from 200, 400, 600 and 800 Re, and the heat fux input varies from 75,000, 100,000, 125,000, and 150,000 W/m2. The following equations show boundary conditions from Table [3.](#page-6-0)

5 Data Reduction

In an MCHS, several parameters are important for numerical calculations and evaluating its thermal performance. Here are some of the equations that have been used, such as the bulk temperature of the fuid, the average temperature of the MCHS wall, heat transfer coefficient, average Nusselt number, pressure drop, and thermal performance factor.

The fluid's bulk temperature refers to its average temperature as it enters or exits the microchannels. It represents the overall thermal behavior of the fluid in the heat sink. The bulk temperature is denoted by T_f and can be calculated using the following equation [[36](#page-15-23)]:

Table 2 Thermophysical properties

$$
T_{f x} = \frac{\int_{A_c} \rho u C_p T \, dA_C}{\int_{A_c} \rho u C_p \, dA_C} \tag{5}
$$

The MCHS wall's average temperature represents the heat sink's thermal behavior. Tw denotes it and can be calculated using the following equation [[36](#page-15-23)]:

$$
T_{wx} = \frac{1}{w} \int \int_{w} T_w dw \tag{6}
$$

The heat transfer coefficient (h_x) characterizes the heat transfer rate between the fuid and the MCHS wall. It is a measure of the efectiveness of heat transfer in the system. The heat transfer coefficient can be calculated using the following equation [[23\]](#page-15-10):

$$
h_x = \frac{q''A_b}{(T_{wx} - T_{fx})NA_i}
$$
\n⁽⁷⁾

The average Nusselt number (N_u) is a dimensionless parameter that describes the convective heat transfer characteristics of the fuid in the microchannels. It is defned as the ratio of convective heat transfer to conductive heat transfer. The average Nusselt number can be calculated using the following equation [[23\]](#page-15-10):

$$
Nu_x = \frac{h_x D_h}{k_f} \tag{8}
$$

$$
Nu = \frac{1}{L} \int_{L} Nu_x dx
$$
\n(9)

Fig. 2 Representing the numerical setup's domain's border conditions

The pressure drop (ΔP) in the microchannels represents the resistance to fuid fow and is an important consideration in the design of microchannel heat sinks. It can be calculated using the following equation [\[23](#page-15-10)]:

$$
\nabla P = P_{out} - P_{in} \tag{10}
$$

The thermal performance factor (TPF) measures heat transfer efficiency in the microchannel heat sink. It can be defned as the ratio of the heat transfer rate to the pressure drop. The TPF can be calculated using the following equation [[23\]](#page-15-10):

$$
TPF = \frac{\frac{N_u}{N_{\text{uplain}}}}{\left(\frac{\Delta P}{\Delta P_{\text{plain}}}\right)^{1/3}}
$$
(11)

6 Mesh Independency

The grid independence is performed to determine the optimal mesh confguration. Six grids of hexahedral mesh were developed for the MCHS in this study to examine grid independence and verify the accuracy of numerical solutions. Independent meshes with element sizes of 0.3, 0.2, 0.15, 0.1, 0.09, and 0.0.8 mm were tested using a hexahedral mesh. The grid size detail concerning the number of mesh elements is depicted in Table [4.](#page-6-1) Pressure drop for the MCHS fn height of 1.5 mm was measured using water as a coolant to model the heat sinks' performance at a Reynolds number of 400. Figure [3](#page-7-0) shows that the last three

Table 3 Boundary condition of MCHS

grids exhibit little diference in pressure drop results, such as 66.642, 66.844 and 66.957 Pa. The pressure drop deviation was determined to be between 2.91 to 0.1% by comparing data including 105,0674, 143,295, and 203,646, respectively, demonstrating that increasing the number of elements results in more reliable results. Hence, element 1050674 was chosen to represent this work because of its precision and low computational cost. Figure [4](#page-7-1) depicts the meshing of the MCHS with a 1.5 mm fin height at a grid size of 0.1 mm.

7 Model Validation

Figure [5](#page-8-0) depicts the Nusselt numbers for a plain microchannel heat sink at various Reynolds numbers, as reported by different references and the present work. The work shows relatively close agreement with Bhandari et al. [\[45\]](#page-16-3). At Reynolds numbers of 200 and 400, the present work and Bhandari et al. [[45](#page-16-3)] have similar Nusselt number values, with a difference of only about 0.3–0.8, respectively. At Reynolds numbers of 600 and 800, the Nusselt number values from the present work are slightly higher than those from Bhandari et al. [[45](#page-16-3)] but are still within a reasonable range.

On the other hand, the Nusselt number values reported by Yu et al. [[46](#page-16-4)] and Shah and London [[47\]](#page-16-5) are higher than those from the present work. At Reynolds numbers of 200 and 400, the present work shows a diference of $0.5-2.5$ and $1-2.1$ from Yu et al. $[46]$ and Shah and London [\[47\]](#page-16-5), respectively. At Reynolds numbers of 600 and 800, the diference between the present work and the other two studies is even larger, with a diference of 2–3.5 and 1.3–2.6, respectively. The diference may be due to variations in the experimental setup, boundary conditions and measurement techniques used in the various studies. The outcomes of this investigation are in reasonable accord with those of other sources reporting outcomes for comparable Reynolds numbers. Comparing the current work's fndings to those found in the literature helps to prove the validity and trustworthiness of the simulation setup used here.

8 Results

8.1 Heat Transfer Performance

In an MCHS, heat fux is an important parameter as it determines the rate of wasted heat from heat generating component. Several factors, including materials' thermal conductivity, rate of fluid flow, and geometry MCHS influence the heat flux. As the cooling fluid flows through the microchannels, it absorbs heat from the heat-generating component and carries it away from the heat sink. The efective heat fux from the bottom of MCHS to the contact wall area is depicted in Fig. [6.](#page-8-1) It can be observed that the effective heat flux values are lower than the heat flux values for all fn heights and heat fux levels. The reduction in efective heat fux is more signifcant for smaller fn heights than larger ones. The efective heat fux values decrease as the heat fux level increases, indicating a

Table 4 Details of mesh elements concerning grid size

Fig. 3 Efect of mesh element size on pressure drop

reduced heat dissipation rate. The highest efective heat flux values are obtained for the largest fin height of 2 mm and the lowest heat flux rate of 75000W/m^2 . Overall, Fig. [7](#page-8-2) highlights the importance of efective heat fux in determining the thermal performance of MCHS.

Nusselt number is a quantitative measure of the convective heat transfer coefficient, which is a critical parameter in determining the overall performance of an MCHS. A higher Nusselt number leads to better heat transfer efficiency. This means an MCHS with a higher Nusselt number can dissipate more heat per unit area and achieve higher cooling performance. Higher Nusselt numbers may require higher pumping power or pressure drop, increasing energy consumption and decreasing overall system efficiency. Therefore, there is a trade-off between achieving higher Nusselt numbers and minimizing the energy consumption of the MCHS system.

Figure [7](#page-8-2) shows that, as height increases, thermal resistance decreases, indicating better thermal performance of the MCHS. This is because higher fn heights provide more surface area for heat dissipation. Adding SiO2 nanoparticles to the water signifcantly improves the thermal performance of the MCHS at all fn heights and mass fow rates. Because of their excellent thermal conductivity, SiO2 nanoparticles speed up heat flow from the fluid to the fins. At low mass flow rates (200 and 400), the difference in thermal resistance between water and SiO2/water is relatively small. However, at higher mass fow rates (600 and 800), the benefts of using SiO2/water become more signifcant. The highest thermal resistance values are observed at the lowest fn height of 0.5 mm. This is because lower fn heights provide less surface area for heat dissipation, resulting in poorer thermal performance. The thermal resistance values decrease as the mass fow rate increases, indicating that higher fow rates result in better thermal performance. However, at very high flow rates, the benefits of increased flow rate may be offset by increased pressure drop and pumping power.

8.2 Fluid Flow Characteristics

Using SiO2/water as a coolant and a heat fux of 125,000, Figs. [8](#page-9-0) and [9](#page-9-1) show the velocity contour in the middle of the plain in the $X & Y$ direction of the MCHS. The crosssectional velocities increase as the fuid passes through the passage available between the MCHS fns. There is a decrease in velocity at the backside of steep angles of the fn cross-section, where the dead zones or areas of zero

Fig. 4 Hexahedral meshing of MCHS for 1.5 mm of fin height

Fig. 5 Validation of the present work concerning Nu. and Re

velocity often occur. It can be observed for the cases or scenarios in the study. The heat transmission properties of MCHS are very sensitive to fuid fow patterns. Understanding the coolant flow stream, circulation, and interaction pattern across triangular pin fns requires understanding the coolant fow properties. A shear layer is generated when fluid flows over the fin of a pin because of the velocity diference between the fuid and the pin's fxed surface. Downstream of the fn, this shear layer generates vortices or eddies, which eventually merge into a wake, as shown in Fig. [10](#page-10-0) at 600 Re and heat fux of 125000W/m2. The rear of the fns creates a wake or revolving vortices. Low velocities and high pressures in the wake zone cause to decrease in the heat transfer coefficient and an increase in thermal resistance.

Fig. 6 Efective heat fux concerning diferent fn heights at diferent heat fuxes

Fig. 7 Efective heat fux concerning diferent fn heights at diferent heat fux

8.3 Temperature Distributions

The temperature distribution in the working fluid is an important measure of thermal performance since it reveals where the heat is concentrated. The efficacy of MCHS is diminished by thermal maldistribution caused by high temperatures in localized areas. The heat transfer coefficient is enhanced due to the triangular pin fns' ability to expand the available heat transfer surface area and increase coolant turbulence. Employing triangular pin fns may infuence the thermal boundary layer and heat transport properties. Inducing vortices in the coolant flow, like the triangle fins, may help with mixing and heat transmission. On the other hand, these vortices may lead to fow separation and decreased heat transmission in certain areas.

At a heat flow of 150000W/m^2 , Fig. [11](#page-10-1) depicts the contact wall temperature distribution across the MCHS at various fin heights at different Re. It can be observed that, with an increase in Re from 200 to 800, the contact wall temperature decreases. It is noticed that the highest decrease in contact wall temperature is at the fin height of 1.5 mm of open MCHS with nano SiO2/water as a coolant for the different Re. In the case of water as a coolant, it is observed that 2.0 mm of fin height of closed MCHS has the lowest contact wall temperature. The difference in temperature of open and closed MCHS, i.e., 1.5 mm fin height and 2.0 mm fin height using nano SiO2/water as a coolant for 200, 400, 600 and 800 Re, is 1.96, 1.82, 1.85 and 2.04, respectively. The reason for the drop in contact wall temperature of the open MCHS compared to closed MCHS is that increased available open space makes this feasible by increasing the net convective surface area responsible

Fig. 8 Contour of velocity at the mid plain of fn height in X-direction at 125,000 heat fux and 600 Re. No. Using SiO2/water as a coolant

Fig. 9 Contour of velocity at the mid plain of the heat sink in Y-direction at 125,000 heat fux and 600 Re using SiO2/water as a coolant

for heat transfer, and it also allows for a more pronounced flow behavior of the coolant. Therefore, the thermal performance of a heat sink is determined by its convective surface area but also by the flow properties of the fluid within the heat sink.

At a Reynolds number of 800, Fig. [12](#page-11-0) displays the temperature distribution of the various fn heights at the microchannel outlet. It can be observed that the contact wall temperature increases with an increase in heat fux input. Also, increased MCHS fn height leads to decreased contact wall

Fig. 10 Contour of velocity streamline and vortex generation of the heat sink at 125,000 heat fux and 600 Re, using SiO2/water as a coolant

temperature in the case of water as a coolant. Whereas in the case of nano SiO2/water, as a coolant contact wall temperature decreases with a rise in MCHS fn height from 0.5 mm to 1.0 mm and 1.0 mm to 1.5 mm, for the change in MCHS fn height from 1.5 mm to 2.0 mm, the contact wall temperature increases for all the heat fux input.

Figures [13](#page-11-1) and [14](#page-12-0) depicts the temperature contour at the bottom of the heat sink at 125,000 heat fux and 600 Re. No. They are using SiO2/water as a coolant. Typically, the temperature is higher near the inlet region of the microchannel heat sink due to the incoming hot fuid, which gradually decreases towards the outlet. The pin fins can cause localized temperature gradients, leading to hot and cold spots in the channel. The sharp edges of the triangular fins can induce vortices in the coolant flow, improving the mixing and heat transfer and decreasing temperature. Increasing the MCHS fn height results in a dramatic drop in temperature. It can be observed that the entrance fns towards the inlet are substantially cooler than the fns towards the outlet. The observed temperature in the wake zone, where the vertices are produced, is maintained at a somewhat lower temperature for 1.5 mm of MCHS fn height compared to 2.0 mm of MCHS fin height.

Fig. 11 Efective heat fux concerning diferent fn heights at diferent heat fux

8.4 Pressure Drop

Since the coolant fow rate is afected by pressure drop, the heat transfer rate and thermal performance of MCHS are also impacted. In MCHS, heat transfers efficiently because the channels are tiny yet have a high surface area to volume

Fig. 12 Efective heat fux concerning diferent fn heights at diferent heat fux

ratio. However, compared to standard MCHS, this causes a greater pressure drop. Pressure drop, caused by frictional losses, often rises with flow rate. At high flow rates, the pressure drop may reach a critical value, beyond which flow instabilities can occur, resulting in reduced heat transfer efficiency and even flow reversal. The effects of pressure drop in MCHS can be signifcant. High-pressure drops can lead to increased pumping power and energy consumption, which can affect the overall efficiency of the cooling system. Also, high-pressure drops can result in uneven fow

distribution among the channels, leading to hot spots and reduced cooling performance in certain heat sink regions. Therefore, it is important to carefully consider the pressure drop behavior and its efects in MCHS for optimal thermal management.

According to Fig. [15](#page-12-1), the resistance to flow rises with a higher Reynolds number as the pressure drop increases for both water and SiO2/water fuid as the Reynolds number increases. It is seen that the SiO2/water fuid has a higher pressure drop than water at all Reynolds numbers, indicating that it is more viscous and, thus, harder to flow through the channel. For both fuids, increasing pressure drop increases with increasing fn height, suggesting that fn height is important in determining pressure drop. This might be because the fns provide greater resistance to air passage. The greatest pressure reductions are seen for water and SiO2/water fuids at a fn height of 2 and a Reynolds number of 800.

At Reynolds number 200, the pressure drop for water is between 8.86 to 31.66, while the pressure drop for SiO2/ water is between 12.62 to 42.48. Similarly, at Reynolds number 800, the pressure drop for water is between 58.48 to 237.85, while for SiO2/water, it is between 77.03 to 286.96. However, it's worth noting that the pressure drop for SiO2/water increases slower than for water as the Reynolds number increases. This could be due to nanoparticles in the SiO2/water mixture, which may alter the fluid flow and reduce turbulence. Overall, SiO2 nanoparticles in water

Fig. 13 Contour of temperature at the bottom of the heat sink at 125,000 heat fux and 600 Re. No. Using SiO2/water as a coolant

Fig. 14 Contour of temperature at the mid plain of the fn height at 125,000 heat fux and 600 Re. No. Using SiO2/water as a coolant

increase the fow resistance, leading to a higher pressure drop. Still, the efect is not signifcant enough to completely outweigh the potential benefts of using SiO2/water, such as improved thermal conductivity. Figure [16](#page-13-0) depicts the pressure drop contour at the mid plain of fin height at $125,000$ heat fux and 600 Re. No. Using SiO2/water as a coolant. It is easily observed that as the height of the fns increases, the pressure drop likewise increases and that the pressure continues to fall as the fuid moves along the channel between the fns and toward the outlet.

8.5 Performance Evaluation Criteria Index

The heat transfer rate and pressure drop are metrics used to assess MCHS's overall efficiency. The TPF evaluation criterion index provides a means of calculating their relative importance. Plain MCHS is the standard in commercial samples. All other forms were normalized. If the TPF for a given example is more than 1, then its performance is better than that of the baseline MCHS. The importance of TPF in MCHS design is that it provides a quantitative measure of the thermal efficiency of the heat sink. Higher TPF values indicate better heat transfer performance, which is desirable in applications where efficient heat dissipation is critical. By optimizing the TPF, MCHS can achieve better thermal performance while minimizing the pressure drop and fuid flow rate.

Fig. 15 Efective heat fux concerning diferent fn heights at diferent heat fux

Figure [17](#page-13-1) depicts the TPF at diferent Reynolds numbers for diferent fn heights and coolants. It is seen that SiO2/ water as a working fuid generally provides higher TPF values than water at all fn heights, indicating better heat transfer performance. At each fn height, the TPF values for SiO2/ water are generally higher than those for water, indicating the superior thermal performance of SiO2/water. For a fn height of 1.0 mm with water coolant, the TPF values are

Fig. 16 Contour of pressure drop at the mid plain of fn height at 125,000 heat fux and 600 Re. No. Using SiO2/water as a coolant

consistently higher than for other fn heights, indicating that this is the most efective fn height for water as a coolant. Similarly, for a fn height of 1.0 mm with SiO2/water coolant, the TPF values are consistently higher than for other fn heights, indicating that this is the most effective fin height for SiO2/water coolant. It is observed that the diference in TPF of using water and nano SiO2/water as a coolant at a fn height of 1.0 mm is 0.198, 0.323, 0.4065, and 0.423 at 200. 400, 600 and 800 Re, respectively.

Fig. 17 TPF concerning Re at diferent fn heights

9 Conclusions

The present research provided a comprehensive analysis and comparison of open MCHS and closed MCHS with water and SiO2/water nanofuid as cooling fuids. The study focuses on the impact of varying fn height and Reynolds number on the heat transfer potential and overall thermal performance of the MCHS. The results highlight the efectiveness of SiO2 nanoparticles in improving thermal conductivity and heat transfer performance while also noting the potential drawbacks of increased pressure drop at higher flow rates.

- Optimal fn height was found to be crucial in maximizing both heat transmission and the characteristics of fuid flow.
- SiO2/water nanofluid showed better thermal performance than water at all fn heights and mass fow rates.
- SiO2/water increases the fow resistance, leading to a higher pressure drop. Still, the effect is not significant enough to completely outweigh the potential benefts of using SiO2/water, such as improved thermal conductivity and thermal performance factor.
- Heat transfer parameter Nusselt no. significantly increases by using nano SiO2/water as coolant. Results indicate that the MCHS with 1.5 mm of fin height provides the highest heat transfer with a maximum value of Nu is 53.02 nano SiO2/water as a coolant. In contrast,

water as a coolant in MCHS with 2.0 mm fin height provides the highest heat transfer value of Nu is 38.68.

- Pressure drop increased with increasing fin height for water and SiO2/water fuids. Results indicate maximum pressure drops of 187.90 and 286.96 Pa at the fn height of 2.0 mm for water and nano SiO2/water as a coolant, respectively.
- The MCHS with 1.0 mm fin height provides the highest TPF of about 2.17 and 1.75 for nano Sio2/water and water as a coolant. The results suggest that SiO2/water nanofuid is a promising coolant for MCHS, providing improved TPF by 0.42 compared to water at 1.0 mm of fin height.

The fndings of this study can be used as a basis for designing and optimizing microchannel heat sinks for various applications, including electronic cooling and renewable energy systems.

10 Future Scope

The present study provides valuable insights into the thermal and fow characteristics of open MCHS and closed MCHS. However, several areas for future research could expand on this work, such as:

- 1. Investigating the efect of diferent nanoparticles and their concentrations on the thermal and flow characteristics of the MCHS.
- 2. Examining the impact of other parameters, such as fn thickness and spacing, on the performance of the MCSH.
- 3. Analysing the long-term reliability and durability of the heat sink under diferent operating conditions.
- 4. Exploring the application of the MCHS in other felds, such as electronics, renewable energy, and aerospace.
- 5. Developing optimisation techniques to determine the optimal combination of parameters for the MCHS design.

By addressing these future research directions, we can improve our understanding of the MCHS technology and enhance its performance and reliability in various applications.

Authors' Contributions Mohammed Anees Sheik and Beemkumar N Conceived the idea of the work and designed the experiments.

Arun Gupta, Amandeep Gill and G.M. Lionus Leo Performed the experiments and analysed the data.

Yuvarajan Devarajan & Ravikumar Jayapal supervised the study.

Data availability Not applicable.

Code Availability Not applicable.

Declarations

Ethics Approval Not applicable.

Consent to Participate Not applicable.

Consent for Publication Not applicable.

Competing interests The authors declare no competing interests.

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